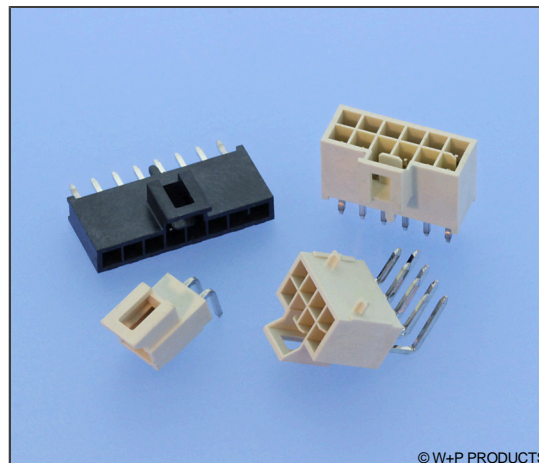


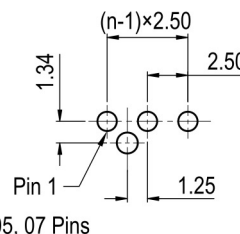
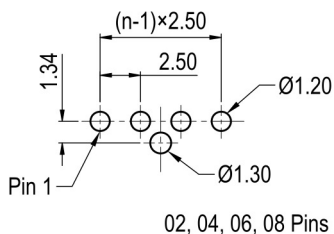
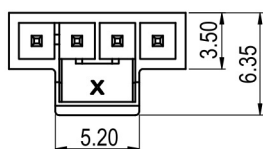
Crimp Rast Wannenstiftleisten RM 2.5mm, gerade/gewinkelt, 1-/2-reihig Friction Lock Pin Headers 2.5mm Pitch, Straight/Right-Angled, Single/Double Row

Technische Daten / Technical Data

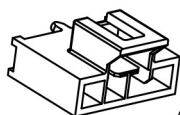
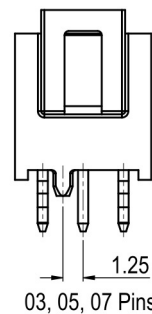
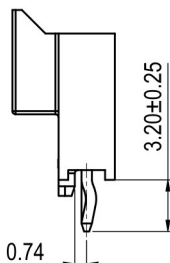
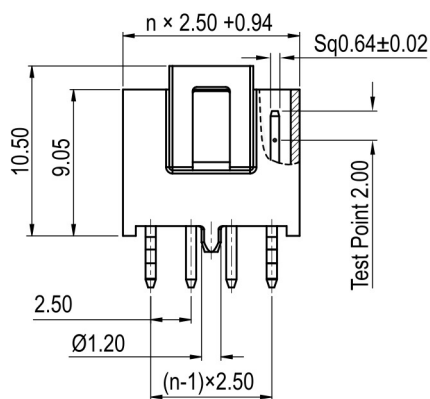
Gehäuse	Thermoplast, nach UL94 V-0
Shell	Thermoplastic, rated UL94 V-0
Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Kupferlegierung
Contact Material	Copper alloy
Kontaktoberfläche	Zinn über Nickel
Contact Surface	Tin plated over nickel
Durchgangswiderstand	< 20 mΩ
Contact Resistance	< 20 mΩ
Isolationswiderstand	> 1000 MΩ
Insulation Resistance	> 1000 MΩ
Spannungsfestigkeit	1500 V AC
Test Voltage	1500 V AC
Nennspannung	250 V AC/DC
Voltage Rating	250 V AC/DC
Nennstrom	6 A
Current Rating	6 A
Temperaturbereich	-25 °C ... +105 °C
Temperature Range	-25 °C ... +105 °C
Verarbeitung	Reflow 255 °C für 5 Sekunden
Processing	Reflow 255 °C for 5 seconds



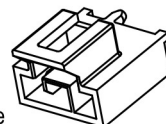
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Recommended PCB Layouts
Recommended PCB Thickness 1.6~2.4mm



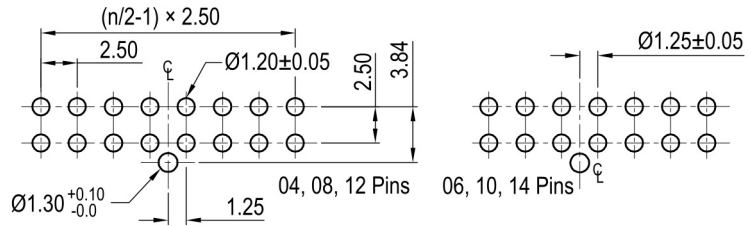
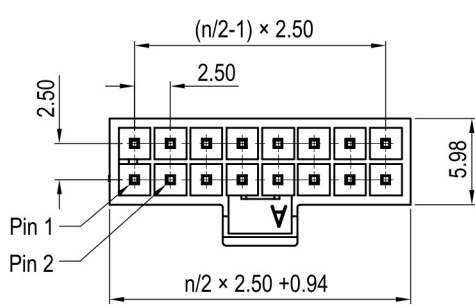
Key A
(black housing)



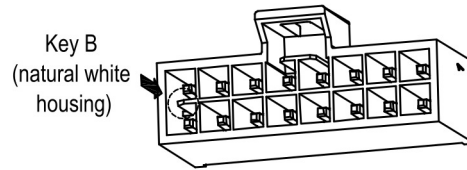
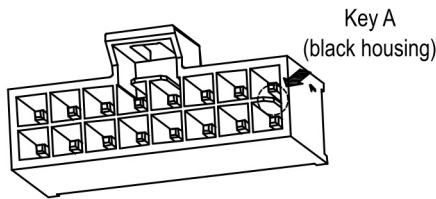
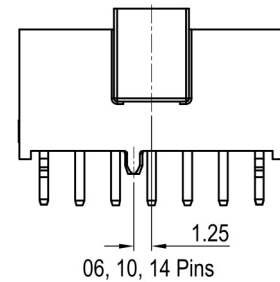
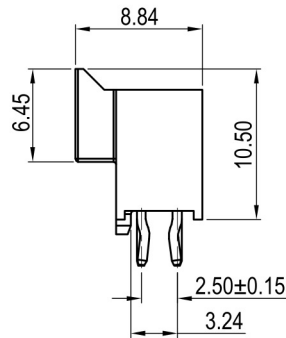
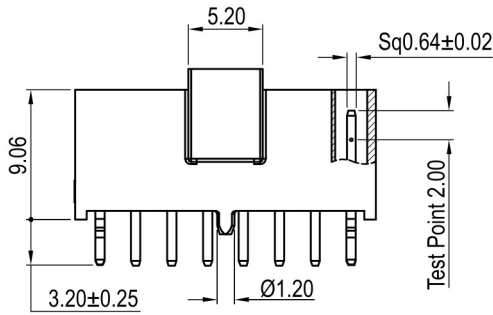
Key B
(natural white housing)

530

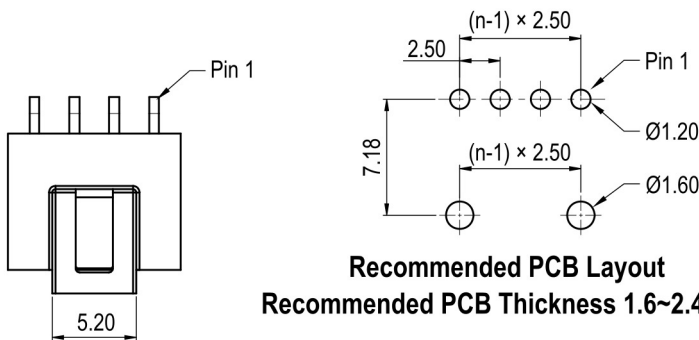
Crimp Rast Wannenstiftleisten RM 2.5mm, gerade/gewinkelt, 1-/2-reihig Friction Lock Pin Headers 2.5mm Pitch, Straight/Right-Angled, Single/Double Row



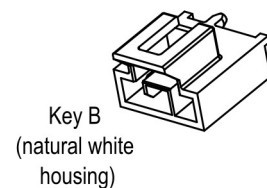
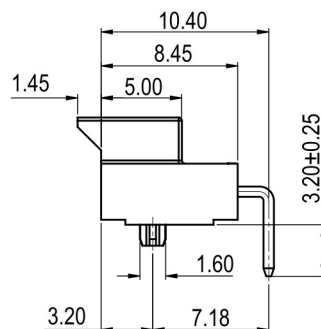
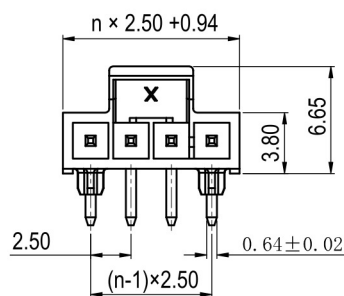
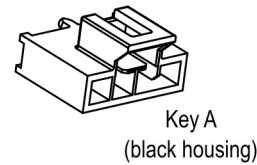
Recommended PCB Layouts
Recommended PCB Thickness 1.6~2.4mm



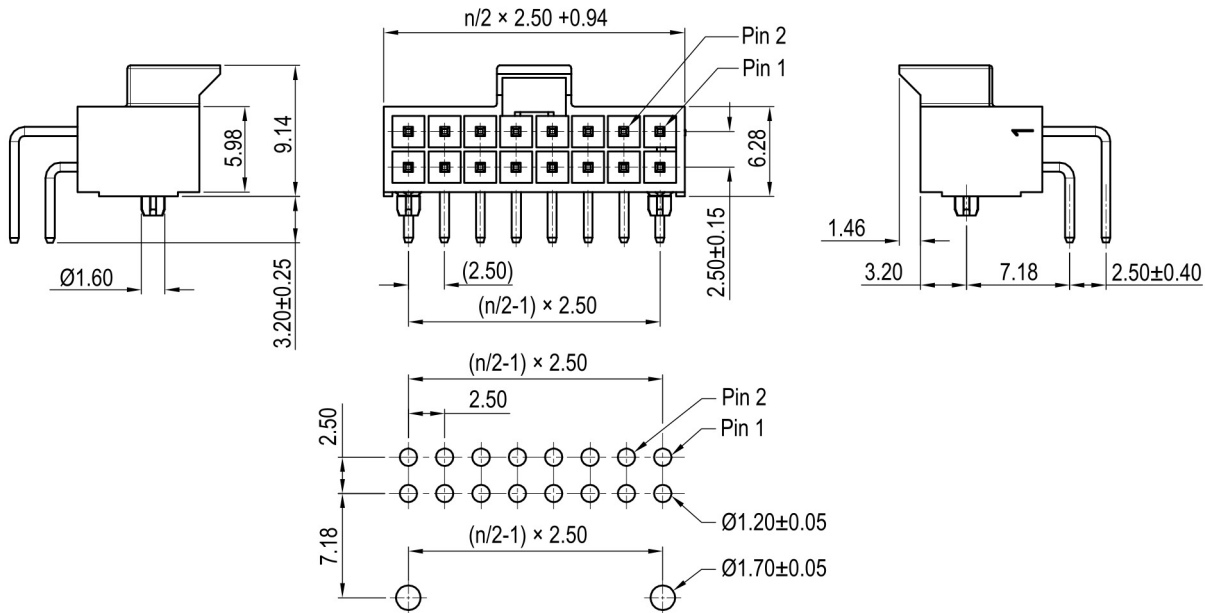
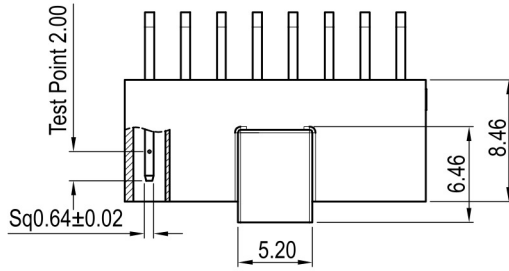
Series	Contacts*	Type	Rows*	Key*	Plating
530	06 02-08 Einreihig Single row 04-16 Zweireihig Double row	3 3 Stiftleiste gerade Box header, vertical	2 1 Einreihig Single row 2 Zweireihig Double row	1 1 Key A, schwarz Key A, black 2 Key B, naturweiß Key B, natural	50 50 Sn



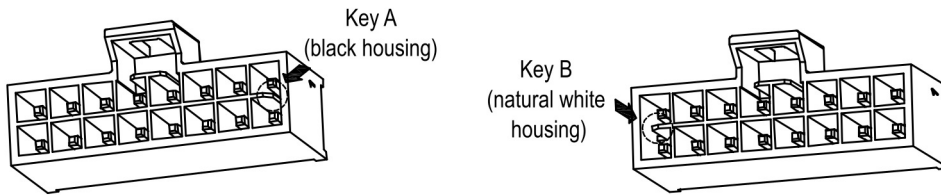
Recommended PCB Layout
Recommended PCB Thickness 1.6~2.4mm



Crimp Rast Wannenstiftleisten RM 2.5mm, gerade/gewinkelt, 1-/2-reihig Friction Lock Pin Headers 2.5mm Pitch, Straight/Right-Angled, Single/Double Row



Recommended PCB Layouts
Recommended PCB Thickness 1.6~2.4mm



Series	Contacts*	Type	Rows*	Key*	Plating
530	12 02-08 Einreihig Single row 04-16 Zweireihig Double row	4 4 Stiftleiste gewinkelt Box header, horizontal	2 1 Einreihig Single row 2 Zweireihig Double row	1 1 Key A, schwarz Key A, black 2 Key B, naturweiß Key B, natural	50 50 Sn

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

Reflow-Lötverfahren

Reflow Soldering Information

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	untere Temperaturangabe [°C]
Verweildauer oberhalb T_L	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	Lower Temperature [°C]
Duration above T_L	Acc. to datasheet [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	Upper Temperature [°C]
Duration Peak Temperature	Acc. to datasheet [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

